



## RF741 Rework Flux No-Clean Electronic-Grade

### Product Description

Kester RF741 is a high-viscosity, no-clean flux designed for electronic component rework and repair applications. RF741 has a gel-like consistency and is easily applied by syringe dispensing. RF741 can be precisely dispensed onto a specific area that needs flux. After being dispensed, RF741 stays in place until soldering occurs. Traditional problems experienced with controlling the application of low solids no-clean liquid fluxes are eliminated. RF741 has excellent performance in applications requiring a flux having good thermal stability such as surface mount component repair. RF741 is the ideal choice for QFP or BGA semi-automated rework operations. In addition, RF741 is well suited for use with through-hole repair operations where solder fountain or controlled solder reservoir is being used for selective component removal and repair. Residues that remain on surfaces after soldering are almost colorless, leaving a very cosmetically appealing repair. The residue has high electrical resistance and can be left on the assembly after soldering. Residues are compatible with all no-clean fluxes in the Kester product line. RF741 can be used in combinations with Kester no-clean cored wire solders and no-clean solder pastes, as well as no-clean liquid fluxes without any compatibility risks.

### Performance Characteristics:

- Compatible with most no-clean chemistries
- Leaves bright/shiny solder joints after reflow
- Classified as ROL0 per J-STD-004
- Compliant to Bellcore GR-78

### RoHS Compliance

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive, 2015/863 for the stated banned substances.

### Physical Properties

**Viscosity (typical):** 180 poise  
Malcom Viscometer @ 10rpm and 25°C

**Acid Number (typical):** 75.0 mg KOH/g of flux  
Tested to J-STD-004, IPC-TM-650, Method 2.3.13

### Reliability Properties

**Copper Mirror Corrosion:** Low  
Tested to J-STD-004, IPC-TM-650, Method 2.3.32

**Chloride and Bromides:** None Detected  
Tested to J-STD-004, IPC-TM-650, Method 2.3.35

**Surface Insulation Resistivity (SIR):** Pass  
Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

**Corrosion Test:** Low  
Tested to J-STD-004, IPC-TM-650, Method 2.6.15

**Fluorides by Spot Test:** Pass  
Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

**Silver Chromate:** Pass  
Tested to J-STD-004, IPC-TM-650, Method 2.3.33

	Blank	RF741
Day 1	2.5*10 <sup>10</sup> Ω	4.0 × 10 <sup>8</sup> Ω
Day 4	1.5*10 <sup>10</sup> Ω	1.6 × 10 <sup>9</sup> Ω
Day 7	1.4*10 <sup>10</sup> Ω	4.0*10 <sup>9</sup> Ω

 **Cleaning**

RF741 is a no-clean chemistry. The residues do not need to be removed for typical applications. If residue removal is required, call Kester Technical Support.

 **Storage, Handling and Shelf Life**

Shelf life is 1 year from the date of manufacture when stored between 0-10°C (32-50°F).

 **Health and Safety**

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet and warning label before using this product.